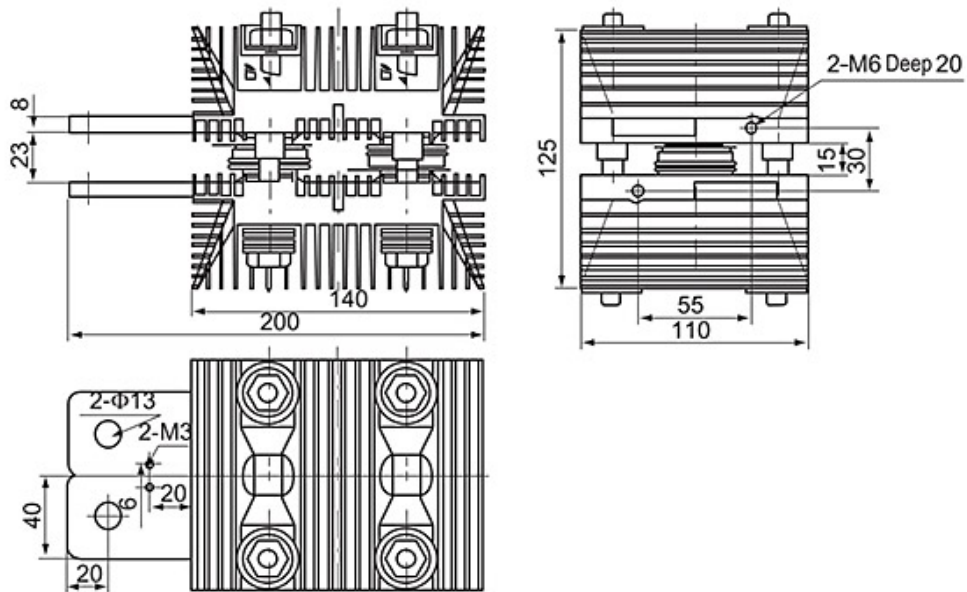




Air-cooling Heatsinks SF13BL for two power semiconductor devices

Type	Surface diameter	Applicable case surface	Mounting force P	Thermal resistance	Flow resistance	Weight	Application
	mm	mm	kN	°C/W	Pa	kg	
SF13BL	∅66	∅34	5.5-25	0.130	45	≥ 4.1	200A-300A element assemblies, and inverse parallel connection power sets, wind speed ≥ 4m/sec



Heatsink SF13BL
forced air-cooling for double disc semiconductor devices